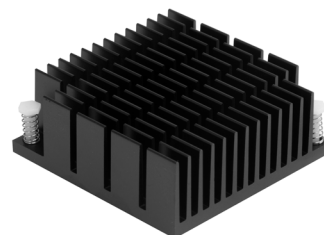


**MODEL:** HSB28-606022 | **DESCRIPTION:** HEAT SINK

**FEATURES**

- BGA design
- top mount
- aluminum alloy



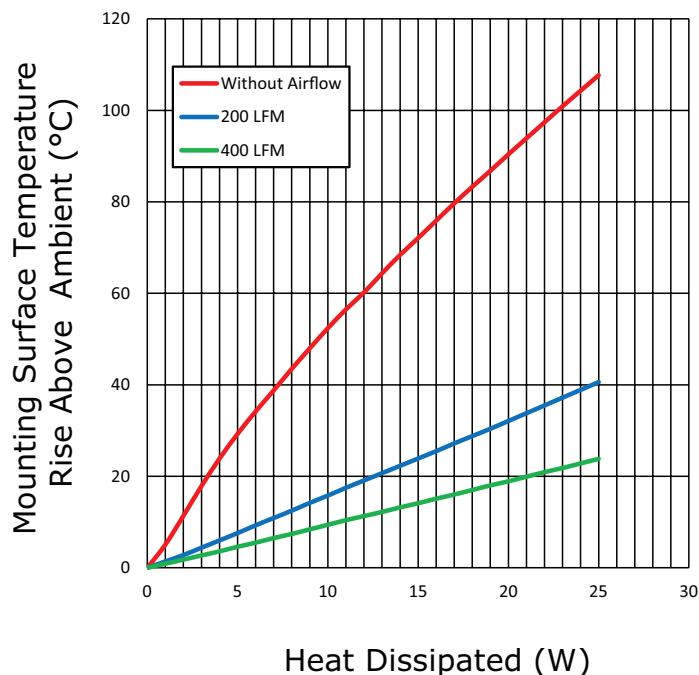
**MODEL**

	thermal resistance <sup>1</sup>				power dissipation <sup>1</sup> @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	
HSB28-606022	4.74	5.1	1.4	0.9	15.83

Note: 1. See performance curves for full thermal resistance details.

**PERFORMANCE CURVES**

Power [W]	Heatsink Temperature Rise Above Ambient (ΔT = T <sub>hs</sub> - T <sub>a</sub> ) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	5.1	1.4	0.9
3	17.9	4.4	2.7
5	29.3	7.6	4.6
7	38.8	10.9	6.5
9	48.0	14.2	8.4
11	56.5	17.5	10.4
13	64.4	20.7	12.2
15	72.1	23.9	14.1
17	79.7	27.2	16.0
19	86.8	30.4	18.0
21	93.9	33.8	19.9
23	100.9	37.2	21.8
25	107.7	40.6	23.8

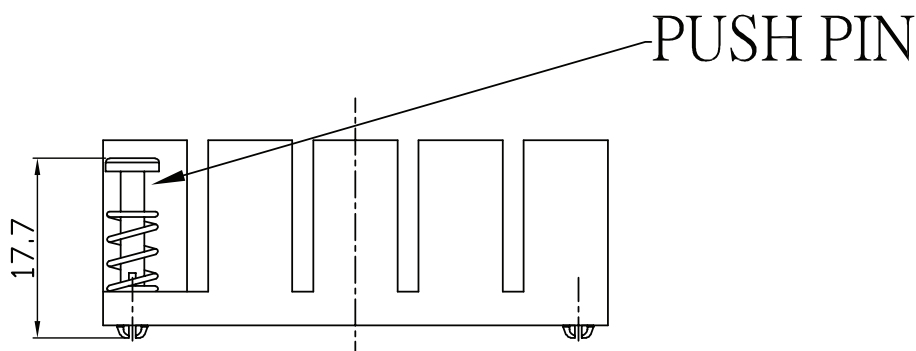
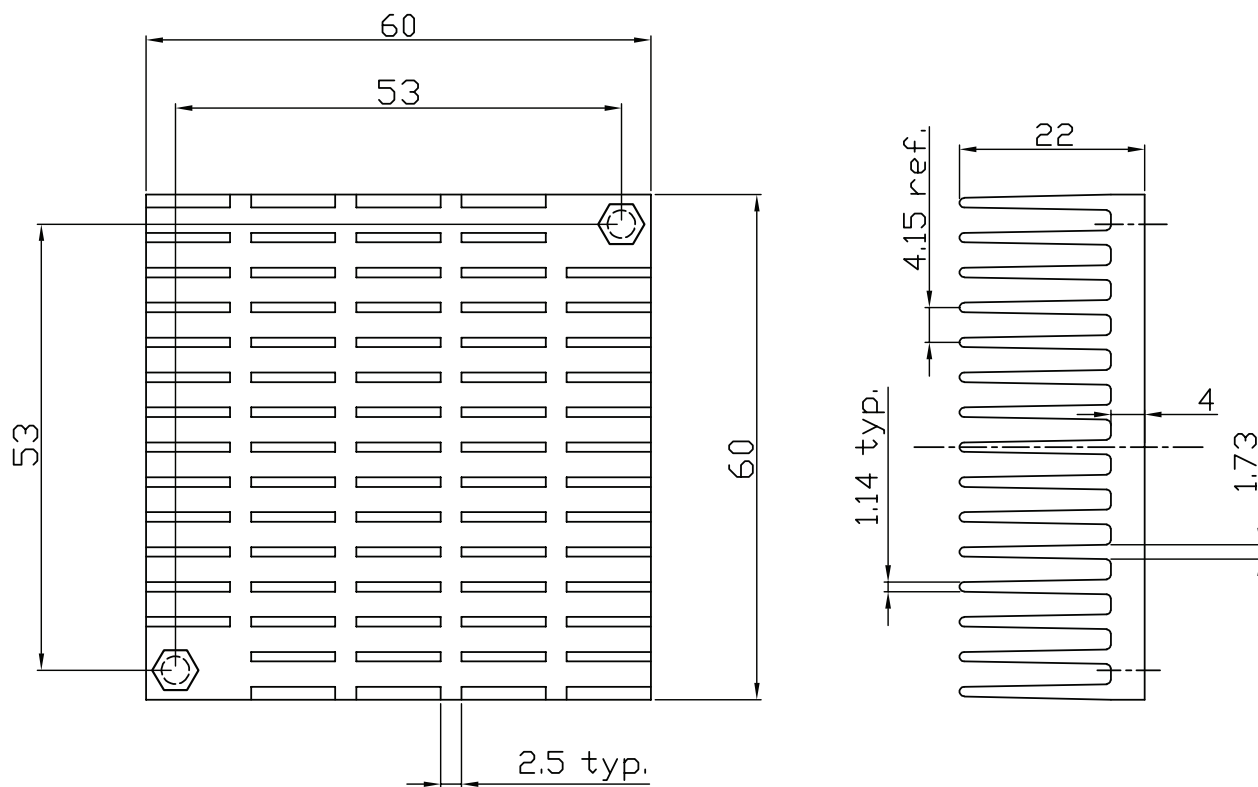


T<sub>hs</sub>: "hot spot" temperature measured on the heatsink  
 T<sub>a</sub>: ambient temperature

## MECHANICAL DRAWING

units: mm  
tolerance: ±0.5 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
PUSH PIN	PA66
SPRING	spring steel, nickel plated
WEIGHT	106.5 g



## REVISION HISTORY

rev.	description	date
1.0	initial release	04/15/2022
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.



CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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